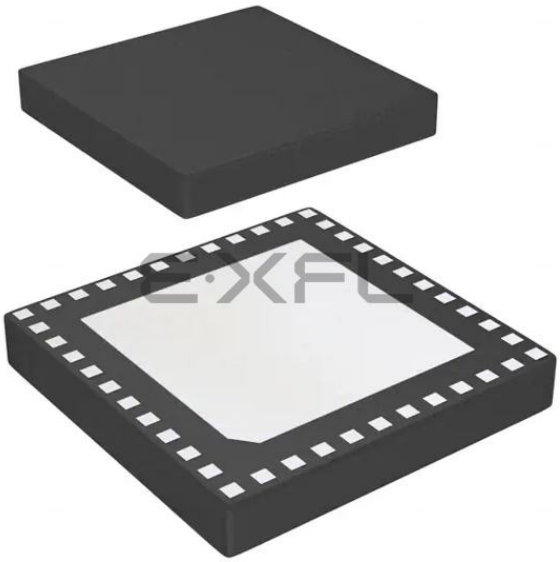

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	16 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 14x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VFTLA Exposed Pad
Supplier Device Package	44-VTLA (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj32mc104-i-tl

TABLE 2: dsPIC33FJ32(GP/MC)101/102/104 DEVICE FEATURES

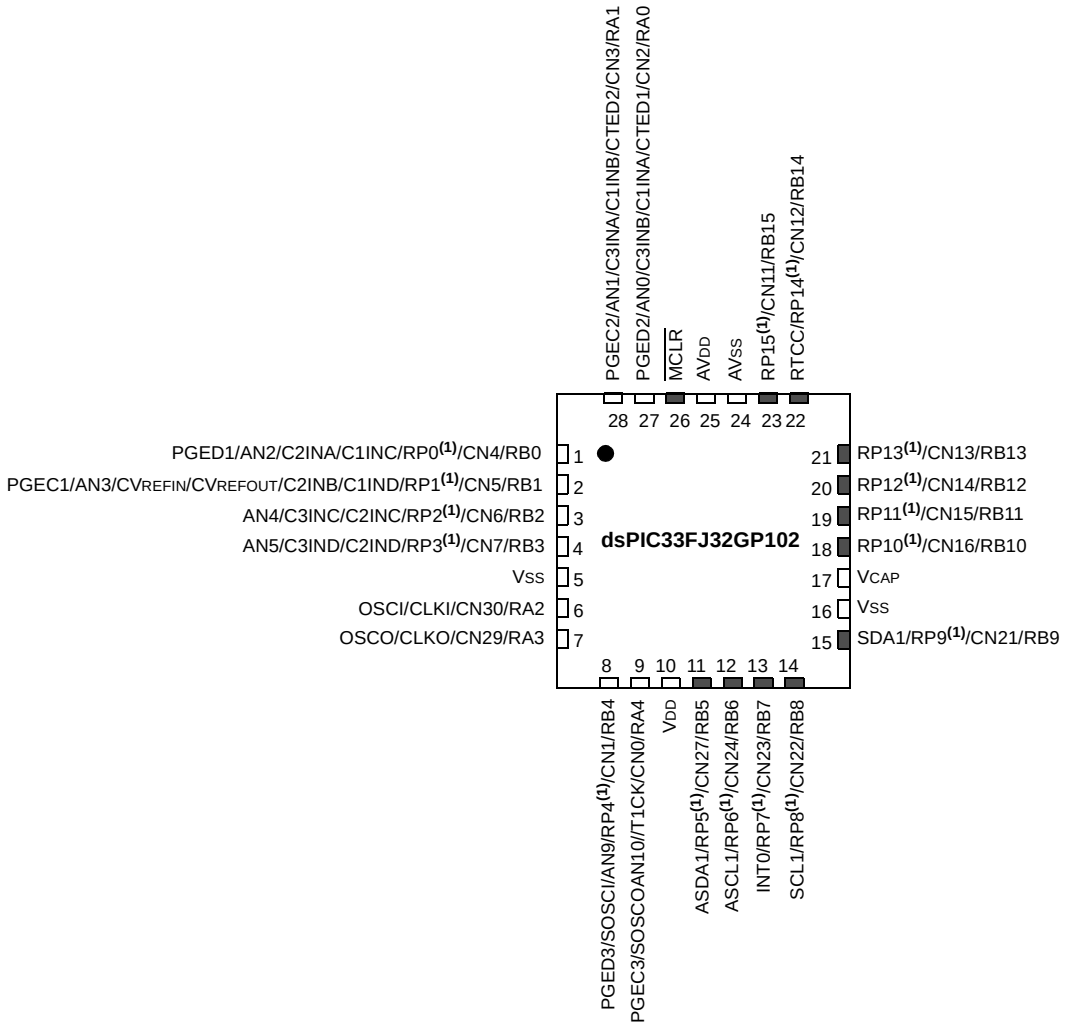
Device	Pins	Program Flash (Kbyte)	RAM (Kbytes)	Remappable Peripherals							Motor Control PWM	PWM Faults	10-Bit, 1.1 Msps ADC	RTCC	I^2C™	Comparators	CTMU	I/O Pins	Packages
				Remappable Pins	16-bit Timer(1,2)	Input Capture	Output Compare	UART	External Interrupts(3)	SPI									
dsPIC33FJ32GP101	18	32	2	8	5	3	2	1	3	1	—	—	1 ADC, 6-ch	Y	1	3	Y	13	PDIP, SOIC
	20	32	2	8	5	3	2	1	3	1	—	—	1 ADC, 6-ch	Y	1	3	Y	15	SSOP
dsPIC33FJ32GP102	28	32	2	16	5	3	2	1	3	1	—	—	1 ADC, 8-ch	Y	1	3	Y	21	SPDIP, SOIC, SSOP, QFN
	36	32	2	16	5	3	2	1	3	1	—	—	1 ADC, 8-ch	Y	1	3	Y	21	VTLA
dsPIC33FJ32GP104	44	32	2	26	5	3	2	1	3	1	—	—	1 ADC, 14-ch	Y	1	3	Y	35	TQFP, QFN, VTLA
dsPIC33FJ32MC101	20	32	2	10	5	3	2	1	3	1	6-ch	1	1 ADC, 6-ch	Y	1	3	Y	15	PDIP, SOIC, SSOP
dsPIC33FJ32MC102	28	32	2	16	5	3	2	1	3	1	6-ch	2	1 ADC, 8-ch	Y	1	3	Y	21	SPDIP, SOIC, SSOP, QFN
	36	32	2	16	5	3	2	1	3	1	6-ch	2	1 ADC, 8-ch	Y	1	3	Y	21	VTLA
dsPIC33FJ32MC104	44	32	2	26	5	3	2	1	3	1	6-ch	2	1 ADC, 14-ch	Y	1	3	Y	35	TQFP, QFN, VTLA

Note 1: Four out of five timers are remappable.
2: Two pairs can be combined to have up to two 32-bit timers.
3: Two out of three interrupts are remappable.

Pin Diagrams (Continued)

28-Pin QFN(2)

■ = Pins are up to 5V tolerant



Note 1: The RPn pins can be used by any remappable peripheral. See Table 1 for the list of available peripherals.

2: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes, and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternately, refer to the AC/DC characteristics and timing requirements information in the *"dsPIC33F Flash Programming Specification for Devices with Volatile Configuration Bits"* (DS70659) for information on capacitive loading limits and pin Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® ICD 3 or MPLAB REAL ICE™.

For more information on ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

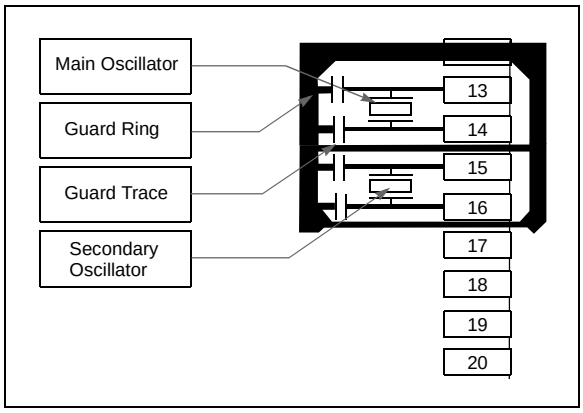
- *"Using MPLAB® ICD 3"* (poster) (DS51765)
- *"MPLAB® ICD 3 Design Advisory"* (DS51764)
- *"MPLAB® REAL ICE™ In-Circuit Debugger User's Guide" (*DS51616)
- *"Using MPLAB® REAL ICE™"* (poster) (DS51749)

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 8.0 "Oscillator Configuration"** for details).

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



3.0 CPU

Note 1: This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"CPU"** (DS70204) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 CPU module has a 16-bit (data) modified Harvard architecture with an enhanced instruction set, including significant support for DSP. The CPU has a 24-bit instruction word with a variable length opcode field. The Program Counter (PC) is 23 bits wide and addresses up to 4M x 24 bits of user program memory space. The actual amount of program memory implemented varies by device. A single-cycle instruction prefetch mechanism is used to help maintain throughput and provides predictable execution. All instructions execute in a single cycle, with the exception of instructions that change the program flow, the double-word move (`MOV.D`) instruction and the table instructions. Overhead-free program loop constructs are supported using the `DO` and `REPEAT` instructions, both of which are interruptible at any point.

The dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices have sixteen, 16-bit Working registers in the programmer's model. Each of the Working registers can serve as a data, address, or address offset register. The 16th Working register (W15) operates as a Software Stack Pointer (SSP) for interrupts and calls.

There are two classes of instruction in the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices: MCU and DSP. These two instruction classes are seamlessly integrated into a single CPU. The instruction set includes many addressing modes and is designed for optimum C compiler efficiency. For most instructions, dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices are capable of executing a data (or program data) memory read, a Working register (data) read, a data memory write and a program (instruction) memory read per instruction cycle. As a result, three parameter instructions can be supported, allowing A + B = C operations to be executed in a single cycle.

A block diagram of the CPU is shown in Figure 3-1, and the programmer's model for the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 is shown in Figure 3-2.

3.1 Data Addressing Overview

The data space can be addressed as 32K words or 64 Kbytes and is split into two blocks, referred to as X and Y data memory. Each memory block has its own independent Address Generation Unit (AGU). The MCU class of instructions operates solely through the X memory AGU, which accesses the entire memory map as one linear data space. Certain DSP instructions operate through the X and Y AGUs to support dual operand reads, which splits the data address space into two parts. The X and Y data space boundary is device-specific.

Overhead-free circular buffers (Modulo Addressing mode) are supported in both X and Y address spaces. The Modulo Addressing removes the software boundary checking overhead for DSP algorithms. Furthermore, the X AGU circular addressing can be used with any of the MCU class of instructions. The X AGU also supports Bit-Reversed Addressing to greatly simplify input or output data reordering for radix-2 FFT algorithms.

The upper 32 Kbytes of the data space memory map can optionally be mapped into program space at any 16K program word boundary defined by the 8-bit Program Space Visibility Page (PSVPAG) register. The program-to-data-space mapping feature lets any instruction access program space as if it were data space.

3.2 DSP Engine Overview

The DSP engine features a high-speed, 17-bit by 17-bit multiplier, a 40-bit ALU, two 40-bit saturating accumulators and a 40-bit bidirectional barrel shifter. The barrel shifter is capable of shifting a 40-bit value up to 16 bits right or left, in a single cycle. The DSP instructions operate seamlessly with all other instructions and have been designed for optimal real-time performance. The `MAC` instruction and other associated instructions can concurrently fetch two data operands from memory, while multiplying two W registers and accumulating and optionally saturating the result in the same cycle. This instruction functionality requires that the RAM data space be split for these instructions and linear for all others. Data space partitioning is achieved in a transparent and flexible manner through dedicating certain Working registers to each address space.

4.2 Data Address Space

The dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family CPU has a separate 16-bit-wide data memory space. The data space is accessed using separate Address Generation Units (AGUs) for read and write operations. The data memory maps is shown in Figure 4-4.

All Effective Addresses (EAs) in the data memory space are 16 bits wide and point to bytes within the data space. This arrangement gives a data space address range of 64 Kbytes or 32K words. The lower half of the data memory space (that is, when EA<15> = 0) is used for implemented memory addresses, while the upper half (EA<15> = 1) is reserved for the Program Space Visibility area (see **Section 4.6.3 "Reading Data from Program Memory Using Program Space Visibility"**).

Microchip dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices implement up to 2 Kbytes of data memory. Should an EA point to a location outside of this area, an all-zero word or byte will be returned.

4.2.1 DATA SPACE WIDTH

The data memory space is organized in byte-addressable, 16-bit wide blocks. Data is aligned in data memory and registers as 16-bit words, but all data space EAs resolve to bytes. The Least Significant Bytes (LSBs) of each word have even addresses, while the Most Significant Bytes (MSBs) have odd addresses.

4.2.2 DATA MEMORY ORGANIZATION AND ALIGNMENT

To maintain backward compatibility with PIC® MCU devices and improve data space memory usage efficiency, the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family instruction set supports both word and byte operations. As a consequence of byte accessibility, all Effective Address calculations are internally scaled to step through word-aligned memory. For example, the core recognizes that Post-Modified Register Indirect Addressing mode [Ws++] will result in a value of Ws + 1 for byte operations and Ws + 2 for word operations.

Data byte reads will read the complete word that contains the byte, using the LSB of any EA to determine which byte to select. The selected byte is placed onto the LSB of the data path. That is, data memory and registers are organized as two parallel byte-wide entities with shared (word) address decoding but separate write lines. Data byte writes only write to the corresponding side of the array or register that matches the byte address.

All word accesses must be aligned to an even address. Misaligned word data fetches are not supported, so care must be taken when mixing byte and word operations, or translating from 8-bit MCU code. If a misaligned read or write is attempted, an address error trap is generated. If the error occurred on a read, the instruction in progress is completed. If the error occurred on a write, the instruction is executed but the write does not occur. In either case, a trap is then executed, allowing the system and/or user application to examine the machine state prior to execution of the address Fault.

All byte loads into any W register are loaded into the LSB. The MSB is not modified.

A Sign-Extend (SE) instruction is provided to allow user applications to translate 8-bit signed data to 16-bit signed values. Alternately, for 16-bit unsigned data, user applications can clear the MSB of any W register by executing a Zero-Extend (ZE) instruction on the appropriate address.

4.2.3 SFR SPACE

The first 2 Kbytes of the Near Data Space, from 0x0000 to 0x07FF, is primarily occupied by Special Function Registers (SFRs). These are used by the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family core and peripheral modules for controlling the operation of the device.

SFRs are distributed among the modules that they control and are generally grouped together by module. Much of the SFR space contains unused addresses; these are read as '0'.

Note:	The actual set of peripheral features and interrupts varies by the device. Refer to the corresponding device tables and pinout diagrams for device-specific information.

4.2.4 NEAR DATA SPACE

The 8-Kbyte area, between 0x0000 and 0x1FFF, is referred to as the Near Data Space. Locations in this space are directly addressable via a 13-bit absolute address field within all memory direct instructions. Additionally, the whole data space is addressable using the MOV class of instructions, which support Memory Direct Addressing mode with a 16-bit address field or by using Indirect Addressing mode with a Working register as an Address Pointer.

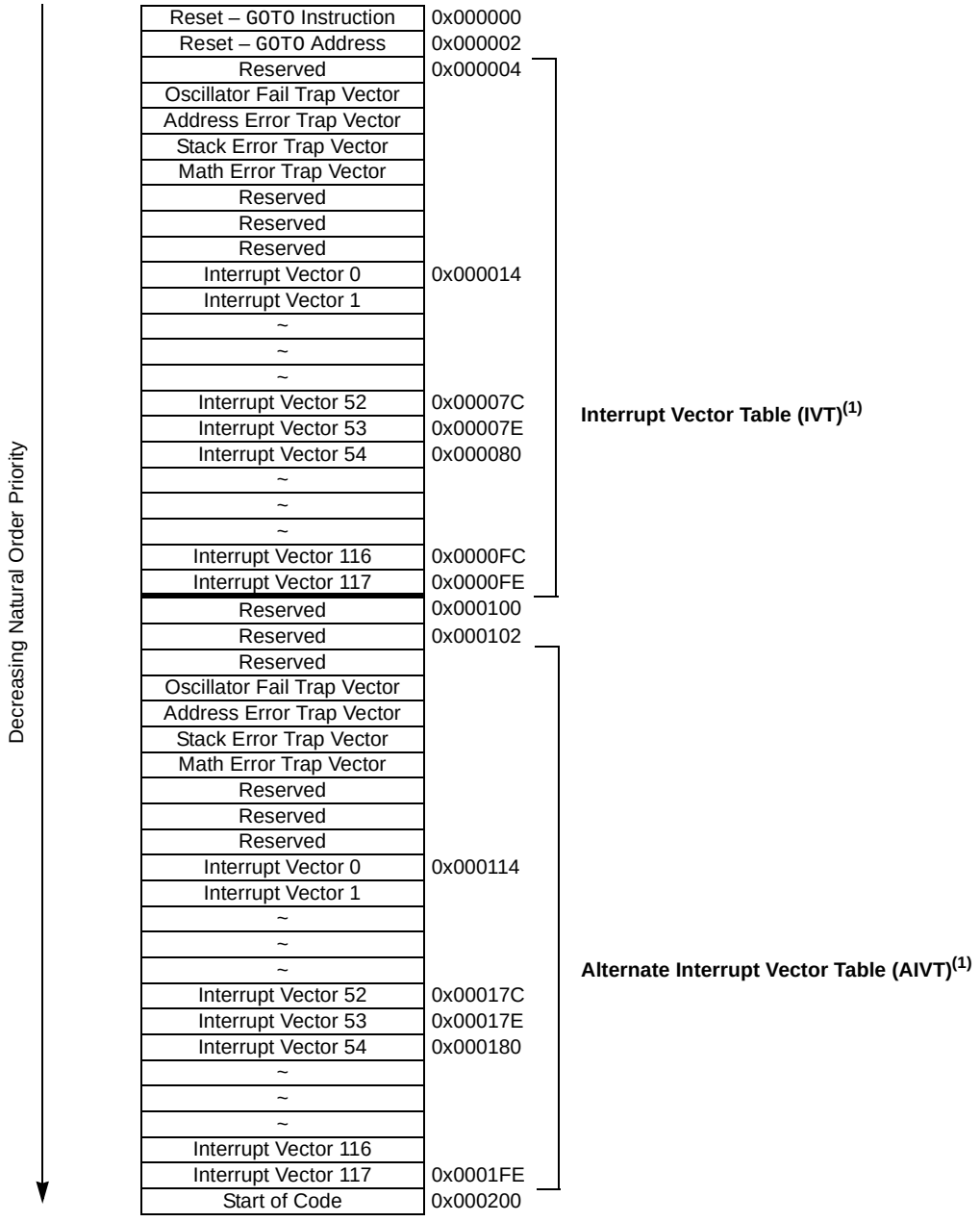
TABLE 4-17: ADC1 REGISTER MAP FOR dsPIC33FJ32(GP/MC)104 DEVICES

File Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
ADC1BUF0	0300	ADC1 Data Buffer 0																xxxx
ADC1BUF1	0302	ADC1 Data Buffer 1																xxxx
ADC1BUF2	0304	ADC1 Data Buffer 2																xxxx
ADC1BUF3	0306	ADC1 Data Buffer 3																xxxx
ADC1BUF4	0308	ADC1 Data Buffer 4																xxxx
ADC1BUF5	030A	ADC1 Data Buffer 5																xxxx
ADC1BUF6	030C	ADC1 Data Buffer 6																xxxx
ADC1BUF7	030E	ADC1 Data Buffer 7																xxxx
ADC1BUF8	0310	ADC1 Data Buffer 8																xxxx
ADC1BUF9	0312	ADC1 Data Buffer 9																xxxx
ADC1BUFA	0314	ADC1 Data Buffer 10																xxxx
ADC1BUFB	0316	ADC1 Data Buffer 11																xxxx
ADC1BUFC	0318	ADC1 Data Buffer 12																xxxx
ADC1BUFD	031A	ADC1 Data Buffer 13																xxxx
ADC1BUFE	031C	ADC1 Data Buffer 14																xxxx
ADC1BUFF	031E	ADC1 Data Buffer 15																xxxx
AD1CON1	0320	ADON	—	ADSIDL	—	—	—	FORM1	FORM0	SSRC2	SSRC1	SSRC0	—	SIMSAM	ASAM	SAMP	DONE	0000
AD1CON2	0322	VCFG2	VCFG1	VCFG0	—	—	CSCNA	CHPS1	CHPS0	BUFS	—	SMPI3	SMPI2	SMPI1	SMPI0	BUFM	ALTS	0000
AD1CON3	0324	ADRC	—	—	SAMC4	SAMC3	SAMC2	SAMC1	SAMC0	ADCS7	ADCS6	ADCS5	ADCS4	ADCS3	ADCS2	ADCS1	ADCS0	0000
AD1CHS123	0326	—	—	—	—	—	CH123NB1	CH123NB0	CH123SB	—	—	—	—	—	CH123NA1	CH123NA0	CH123SA	0000
AD1CHS0	0328	CH0NB	—	—	CH0SB4	CH0SB3	CH0SB2	CH0SB1	CH0SB0	CH0NA	—	—	CH0SA4	CH0SA3	CH0SA2	CH0SA1	CH0SA0	0000
AD1PCFGL	032C	PCFG15	—	—	PCFG<12:0>(1)													0000
AD1CSSL	0330	CSS15	—	—	CSS12:0>(1)													0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: The PCFG<10:9> and CSS<10:9> bits are available in dsPIC33FJ32(GP/MC)104 devices only.

FIGURE 7-1: dsPIC33FJ16(GP/MC)101/102 AND dsPIC33FJ32(GP/MC)101/102/104 INTERRUPT VECTOR TABLE



Note 1: See Table 7-1 for the list of implemented interrupt vectors.

REGISTER 7-16: IPC1: INTERRUPT PRIORITY CONTROL REGISTER 1

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	T2IP2	T2IP1	T2IP0	—	OC2IP2	OC2IP1	OC2IP0
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	IC2IP2	IC2IP1	IC2IP0	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-12 **T2IP<2:0>:** Timer2 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as ‘0’

bit 10-8 **OC2IP<2:0>:** Output Compare Channel 2 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as ‘0’

bit 6-4 **IC2IP<2:0>:** Input Capture Channel 2 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3-0 **Unimplemented:** Read as ‘0’

TABLE 10-1: SELECTABLE INPUT SOURCES (MAPS INPUT TO FUNCTION)(1)

Input Name	Function Name	Register	Configuration Bits
External Interrupt 1	INT1	RPINR0	INT1R<4:0>
External Interrupt 2	INT2	RPINR1	INT2R<4:0>
Timer2 External Clock	T2CK	RPINR3	T2CKR<4:0>
Timer3 External Clock	T3CK	RPINR3	T3CKR<4:0>
Timer4 External Clock	T4CK	RPINR4	T4CKR<4:0>(2)
Timer5 External Clock	T5CK	RPINR4	T5CKR<4:0>(2)
Input Capture 1	IC1	RPINR7	IC1R<4:0>
Input Capture 2	IC2	RPINR7	IC2R<4:0>
Input Capture 3	IC3	RPINR8	IC3R<4:0>
Output Compare Fault A	OCFA	RPINR11	OCFAR<4:0>
UART1 Receive	U1RX	RPINR18	U1RXR<4:0>
UART1 Clear-to-Send	$\overline{\text{U1CTS}}$	RPINR18	U1CTSR<4:0>
SDI1 SPI Data Input 1	SDI1	RPINR20	SDI1R<4:0>(2)
SCK1 SPI Clock Input 1	SCK1	RPINR20	SCK1R<4:0>(2)
SPI1 Slave Select Input	$\overline{\text{SS1}}$	RPINR21	SS1R<4:0>(2)

Note 1: Unless otherwise noted, all inputs use the Schmitt input buffers.

2: These bits are available in dsPIC33FJ32(GP/MC)10X devices only.

REGISTER 18-2: UxSTA: UARTx STATUS AND CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	R/W-0, HC	R/W-0	R-0	R-1
UTXISEL1	UTXINV	UTXISEL0	—	UTXBRK	UTXEN(1)	UTXBF	TRMT
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R-1	R-0	R-0	R/C-0	R-0
URXISEL1	URXISEL0	ADDEN	RIDLE	PERR	FERR	OERR	URXDA
bit 7							bit 0

Legend:	C = Clearable bit	HC = Hardware Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15,13 **UTXISEL<1:0>:** UARTx Transmission Interrupt Mode Selection bits
- 11 = Reserved; do not use
- 10 = Interrupt when a character is transferred to the Transmit Shift Register (TSR) and as a result, the transmit buffer becomes empty
- 01 = Interrupt when the last character is shifted out of the Transmit Shift Register; all transmit operations are completed
- 00 = Interrupt when a character is transferred to the Transmit Shift Register (this implies there is at least one character open in the transmit buffer)

bit 14 **UTXINV:** UARTx Transmit Polarity Inversion bit

If IREN = 0:
- 1 = UxTX Idle state is '0'
- 0 = UxTX Idle state is '1'

If IREN = 1:
- 1 = IrDA encoded, UxTX Idle state is '1'
- 0 = IrDA encoded, UxTX Idle state is '0'

bit 12 **Unimplemented:** Read as '0'

bit 11 **UTXBRK:** UARTx Transmit Break bit
- 1 = Sends Sync Break on next transmission – Start bit, followed by twelve '0' bits, followed by Stop bit; cleared by hardware upon completion
- 0 = Sync Break transmission is disabled or completed

bit 10 **UTXEN:** UARTx Transmit Enable bit(1)
- 1 = Transmit is enabled, UxTX pin is controlled by UARTx
- 0 = Transmit is disabled, any pending transmission is aborted and the buffer is reset; UxTX pin is controlled by port

bit 9 **UTXBF:** UARTx Transmit Buffer Full Status bit (read-only)
- 1 = Transmit buffer is full
- 0 = Transmit buffer is not full, at least one more character can be written

bit 8 **TRMT:** Transmit Shift Register Empty bit (read-only)
- 1 = Transmit Shift Register is empty and transmit buffer is empty (the last transmission has completed)
- 0 = Transmit Shift Register is not empty, a transmission is in progress or queued

bit 7-6 **URXISEL<1:0>:** UARTx Receive Interrupt Mode Selection bits
- 11 = Interrupt is set on UxRSR transfer, making the receive buffer full (i.e., has 4 data characters)
- 10 = Interrupt is set on UxRSR transfer, making the receive buffer 3/4 full (i.e., has 3 data characters)
- 0x = Interrupt is set when any character is received and transferred from the UxRSR to the receive buffer; receive buffer has one or more characters

Note 1: Refer to **"UART"** (DS70188) in the *"dsPIC33/PIC24 Family Reference Manual"* for information on enabling the UART module for transmit operation.

REGISTER 21-9: ALRMVAL (WHEN ALRMPTR<1:0> = 01): ALARM WEEKDAY AND HOURS VALUE REGISTER(1)

U-0	U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x
—	—	—	—	—	WDAY2	WDAY1	WDAY0
bit 15							bit 8

U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	HRTEN1	HRTEN0	HRONE3	HRONE2	HRONE1	HRONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as ‘0’

bit 10-8 **WDAY<2:0>:** Binary Coded Decimal Value of Weekday Digit bits
Contains a value from 0 to 6.

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-4 **HRTEN<1:0>:** Binary Coded Decimal Value of Hour’s Tens Digit bits
Contains a value from 0 to 2.

bit 3-0 **HRONE<3:0>:** Binary Coded Decimal Value of Hour’s Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to this register is only allowed when RTCWREN = 1.

REGISTER 21-10: ALRMVAL (WHEN ALRMPTR<1:0> = 00): ALARM MINUTES AND SECONDS VALUE REGISTER

U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	MINTEN2	MINTEN1	MINTEN0	MINONE3	MINONE2	MINONE1	MINONE0
bit 15							bit 8

U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	SECTEN2	SECTEN1	SECTEN0	SECONE3	SECONE2	SECONE1	SECONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **MINTEN<2:0>:** Binary Coded Decimal Value of Minute's Tens Digit bits
Contains a value from 0 to 5.

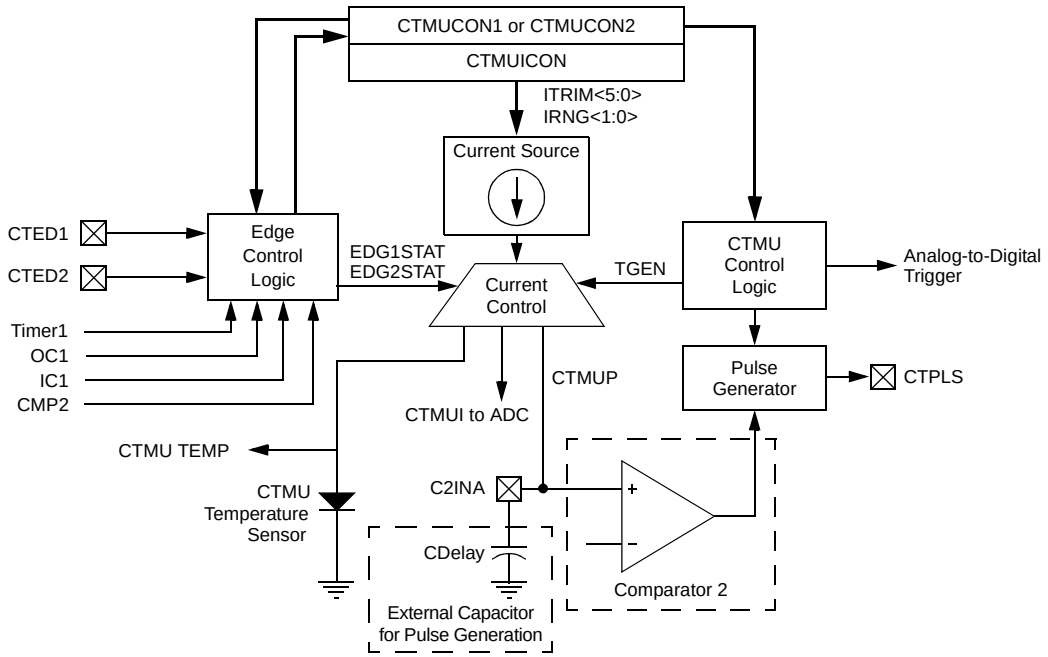
bit 11-8 **MINONE<3:0>:** Binary Coded Decimal Value of Minute's Ones Digit bits
Contains a value from 0 to 9.

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **SECTEN<2:0>:** Binary Coded Decimal Value of Second's Tens Digit bits
Contains a value from 0 to 5.

bit 3-0 **SECONE<3:0>:** Binary Coded Decimal Value of Second's Ones Digit bits
Contains a value from 0 to 9.

FIGURE 22-1: CTMU BLOCK DIAGRAM



Current Control Selection	TGEN	EDG1STAT, EDG2STAT
CTMU TEMP	0	EDG1STAT = EDG2STAT
CTMUI	0	EDG1STAT ≠ EDG2STAT
CTMUP	1	EDG1STAT ≠ EDG2STAT
No Connect	1	EDG1STAT = EDG2STAT

TABLE 26-7: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.	**Typical(1)**	**Max**	**Units**	**Conditions**		
Idle Current (IIDLE): Core Off, Clock On Base Current(2) – dsPIC33FJ16(GP/MC)10X Devices						
DC40d	0.4	1.0	mA	-40°C	3.3V	LPRC (32.768 kHz)(3)
DC40a	0.4	1.0	mA	+25°C		
DC40b	0.4	1.0	mA	+85°C		
DC40c	0.5	1.0	mA	+125°C		
DC41d	0.5	1.1	mA	-40°C	3.3V	1 MIPS(3)
DC41a	0.5	1.1	mA	+25°C		
DC41b	0.5	1.1	mA	+85°C		
DC41c	0.8	1.1	mA	+125°C		
DC42d	0.9	1.6	mA	-40°C	3.3V	4 MIPS(3)
DC42a	0.9	1.6	mA	+25°C		
DC42b	1.0	1.6	mA	+85°C		
DC42c	1.2	1.6	mA	+125°C		
DC43a	1.6	2.6	mA	+25°C	3.3V	10 MIPS(3)
DC43d	1.6	2.6	mA	-40°C		
DC43b	1.7	2.6	mA	+85°C		
DC43c	2	2.6	mA	+125°C		
DC44d	2.4	3.8	mA	-40°C	3.3V	16 MIPS(3)
DC44a	2.4	3.8	mA	+25°C		
DC44b	2.6	3.8	mA	+85°C		
DC44c	2.9	3.8	mA	+125°C		

Note 1: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

2: Base Idle current is measured as follows:

- CPU core is off, oscillator is configured in EC mode, OSC1 is driven with external square wave from rail-to-rail
- CLKO is configured as an I/O input pin in the Configuration Word
- External Secondary Oscillator (SOSC) is disabled (i.e., SOSCO and SOSCI pins are configured as digital I/O inputs)
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD, WDT and FSCM are disabled
- No peripheral modules are operating; however, every peripheral is being clocked (PMDx bits are all zeroed)

3: These parameters are characterized, but not tested in manufacturing.

TABLE 26-12: DC CHARACTERISTICS: PROGRAM MEMORY

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(3)**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
		Program Flash Memory					
D130a	EP	Cell Endurance	10,000	—	—	E/W	-40°C to +125°C
D131	VPR	VDD for Read	VMIN	—	3.6	V	VMIN = Minimum operating voltage
D132b	VPEW	VDD for Self-Timed Write	VMIN	—	3.6	V	VMIN = Minimum operating voltage
D134	TRETD	Characteristic Retention	20	—	—	Year	Provided no other specifications are violated
D135	IDDP	Supply Current during Programming	—	10	—	mA	
D137a	TPE	Page Erase Time	20.1	—	26.5	ms	TPE = 168517 FRC cycles, TA = +85°C, See **Note 2**
D137b	TPE	Page Erase Time	19.5	—	27.3	ms	TPE = 168517 FRC cycles, TA = +125°C, See **Note 2**
D138a	TWW	Word Write Cycle Time	47.4	—	49.3	µs	TWW = 355 FRC cycles, TA = +85°C, See **Note 2**
D138b	TWW	Word Write Cycle Time	47.4	—	49.3	µs	TWW = 355 FRC cycles, TA = +125°C, See **Note 2**

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

2: Other conditions: FRC = 7.37 MHz, TUN<5:0> = b'011111 (for Min), TUN<5:0> = b'100000 (for Max). This parameter depends on the FRC accuracy (see Table 26-18) and the value of the FRC Oscillator Tuning register (see Register 8-3). For complete details on calculating the Minimum and Maximum time, see **Section 5.3 "Programming Operations"**.

3: These parameters are ensured by design, but are not characterized or tested in manufacturing.

TABLE 26-13: INTERNAL VOLTAGE REGULATOR SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristics**	**Min**	**Typ**	**Max**	**Units**	**Comments**
—	CEFC	External Filter Capacitor Value(1)	4.7	10	—	µF	Capacitor must be low series resistance (< 5 ohms)

Note 1: Typical VCAP voltage = 2.5V when VDD ≥ VDDMIN.

TABLE 26-17: PLL CLOCK TIMING SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
OS50	FPLLI	PLL Voltage Controlled Oscillator (VCO) Input Frequency Range(2)	3.0	—	8	MHz	ECPLL and MSPLL modes
OS51	FSYS	On-Chip VCO System Frequency(3)	12	—	32	MHz	
OS52	TLOCK	PLL Start-up Time (Lock Time)(3)	—	—	2	mS	
OS53	DCLK	CLKO Stability (Jitter)(3)	-2	1	+2	%	

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: These parameters are characterized by similarity, but are tested in manufacturing at 7.7 MHz input only.

3: These parameters are characterized by similarity, but are not tested in manufacturing. This specification is based on clock cycle by clock cycle measurements. The effective jitter for individual time bases, or communication clocks used by the user application, are derived from dividing the CLKO stability specification by the square root of "N" (where "N" is equal to FOSC, divided by the peripheral data rate clock). For example, if FOSC = 32 MHz and the SPI bit rate is 5 MHz, the effective jitter of the SPI clock is equal to:

$$\frac{DCLK}{\sqrt{\frac{32}{5}}} = \frac{2\%}{2.53} = 0.79\%$$

TABLE 26-18: AC CHARACTERISTICS: INTERNAL FAST RC (FRC) ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**	
	Internal FRC Accuracy @ 7.37 MHz(1)						
F20a	FRC	-2	±0.25	+2	%	-40°C ≤ TA ≤ -10°C	VDD 3.0-3.6V
F20b	FRC	-1	±0.25	+1	%	-10°C ≤ TA ≤ +85°C	VDD 3.0-3.6V
F20c	FRC	-5	±0.25	+5	%	+85°C ≤ TA ≤ +125°C	VDD 3.0-3.6V

Note 1: Frequency is calibrated at +25°C and 3.3V. TUNx bits may be used to compensate for temperature drift.

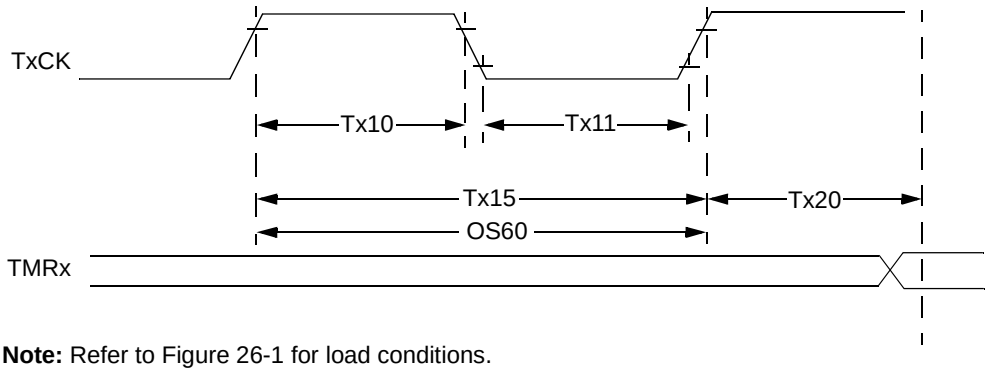
TABLE 26-19: INTERNAL LOW-POWER RC (LPRC) ACCURACY

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**	
	LPRC @ 32.768 kHz(1,2)						
F21a	LPRC	-30	±10	+20	%	-40°C ≤ TA ≤ -10°C	VDD 3.0-3.6V
F21b	LPRC	-20	±10	+30	%	-10°C ≤ TA ≤ +85°C	VDD 3.0-3.6V
F21c	LPRC	-35	±10	+35	%	+85°C ≤ TA ≤ +125°C	VDD 3.0-3.6V

Note 1: Change of LPRC frequency as VDD changes.

2: LPRC accuracy impacts the Watchdog Timer Time-out Period (TWDT1). See **Section 23.4 "Watchdog Timer (WDT)"** for more information.

FIGURE 26-5: TIMER1/2/3 EXTERNAL CLOCK TIMING CHARACTERISTICS



Note: Refer to Figure 26-1 for load conditions.

TABLE 26-22: TIMER1 EXTERNAL CLOCK TIMING REQUIREMENTS(1)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(2)**		**Min**	**Typ**	**Max**	**Units**	**Conditions**
TA10	TTXH	T1CK High Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TA15, N = prescale value (1, 8, 64, 256)
			Asynchronous	35	—	—	ns	
TA11	TTXL	T1CK Low Time	Synchronous mode	Greater of: 20 ns or (TCY + 20)/N	—	—	ns	Must also meet Parameter TA15, N = prescale value (1, 8, 64, 256)
			Asynchronous	10	—	—	ns	
TA15	TTXP	T1CK Input Period	Synchronous mode	Greater of: 40 or (2 TCY + 40)/N	—	—	ns	N = prescale value (1, 8, 64, 256)
OS60	Ft1	SOSC1/T1CK Oscillator Input Frequency Range (oscillator enabled by setting the TCS (T1CON<1>) bit)		DC	—	50	kHz	
TA20	TCKEXTMRL	Delay from External T1CK Clock Edge to Timer Increment		0.75 TCY + 40	—	1.75 TCY + 40	ns	

Note 1: Timer1 is a Type A.

2: These parameters are characterized by similarity, but are not tested in manufacturing.

TABLE 26-36: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING REQUIREMENTS FOR dsPIC33FJ16(GP/MC)10X

AC CHARACTERISTICS			Standard Operating Conditions: 2.4V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP70	TscP	Maximum SCKx Input Frequency	—	—	11	MHz	See **Note 3**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↑ or SCKx Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance	10	—	50	ns	See **Note 4**
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ after SCKx Edge	1.5 TCY + 40	—	—	ns	See **Note 4**

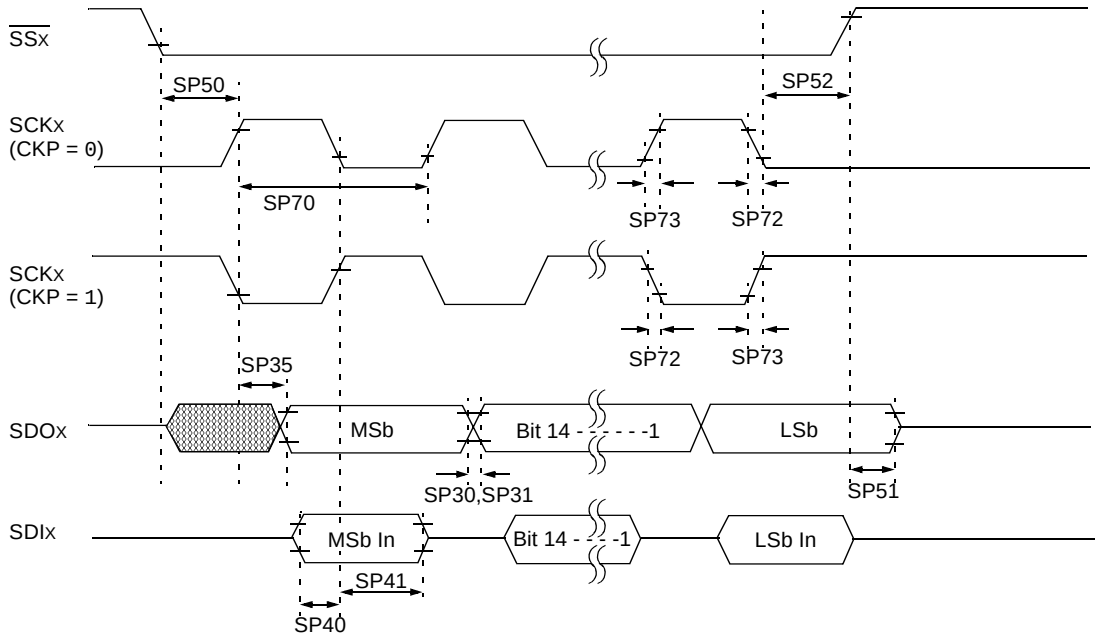
Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 91 ns. Therefore, the SCKx clock generated by the Master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 26-26: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING CHARACTERISTICS FOR dsPIC33FJ32(GP/MC)10X



Note: Refer to Figure 26-1 for load conditions.

TABLE 26-48: 10-BIT ADC MODULE SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V[4] (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ**	**Max.**	**Units**	**Conditions**
10-Bit ADC Accuracy – Measurements with AVDD/AVSS[3]							
AD20b	Nr	Resolution	10 Data Bits			bits	
AD21b	INL	Integral Nonlinearity	-1	—	+1	LSb	VINL = AVSS = 0V, AVDD = 3.6V
AD22b	DNL	Differential Nonlinearity	>-1	—	<1	LSb	VINL = AVSS = 0V, AVDD = 3.6V
AD23b	GERR	Gain Error	3	7	15	LSb	VINL = AVSS = 0V, AVDD = 3.6V
AD24b	EOFF	Offset Error	1.5	3	7	LSb	VINL = AVSS = 0V, AVDD = 3.6V
AD25b	—	Monotonicity	—	—	—	—	Guaranteed[1]
Dynamic Performance (10-Bit Mode)[2]							
AD30b	THD	Total Harmonic Distortion	—	—	-64	dB	
AD31b	SINAD	Signal to Noise and Distortion	57	58.5	—	dB	
AD32b	SFDR	Spurious Free Dynamic Range	72	—	—	dB	
AD33b	FNYQ	Input Signal Bandwidth	—	—	550	kHz	
AD34b	ENOB	Effective Number of Bits	9.16	9.4	—	bits	

Note 1: The Analog-to-Digital conversion result never decreases with an increase in the input voltage and has no missing codes.

2: These parameters are characterized by similarity, but are not tested in manufacturing.

3: These parameters are characterized, but are tested at 20 ksps only.

4: Overall functional device operation at VBOR < VDD < VDDMIN is guaranteed but not characterized. All device analog modules, such as the ADC, etc., will function but with degraded performance below VDDMIN